

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Mizuki NAGAI et al. :
Serial No. NEW : **Attn: APPLICATION BRANCH**
Filed September 17, 2003 : Attorney Docket No. 2003-1338

COPPER-PLATING LIQUID, PLATING
METHOD AND PLATING APPARATUS
(Rule 1.53(b) Divisional
of Serial No. 09/893,624 ,
Filed June 29, 2001)

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In the interest of compact prosecution, please amend the present application as follows: